

Capacitor Materials

ET1812



Pb-Free Solderable End Termination

Description:

ET1812 is a Pb free solderable Ag/Pt end termination designed for use on NPO MLCC (multilayer ceramic chip capacitors). It offers excellent solderability and adhesion.

ET1812 is supplied at a viscosity suitable for machine dip and blot or no blot applications

● Key Benefits :

- Does not contain Pb or Cd
- Suitable rheology for machine dip application
- Excellent solderability and adhesion
- Compatible on NPO dielectrics

● Typical Properties:

Viscosity :

31.5-38.5 Kcps; Brookfield RVT,
SC4-14 spindle and 6R cup at 10 RPM, 25°C.

Solids :

80% ± 1.0%

FOG :

≤ 10 μm (4th scratch)

Solderability :

62Sn/36Pb/2Ag @ 220°C
10 sec dip, RMA flux

>95% Solder Coverage

● Recommended Processing Guidelines:

Drying :

150°C peak drying profile
10 minutes at peak temperature
20 minutes total cycle time

Firing:

Fires at 780-810°C peak temperature
Dwell time of 5-6 minutes at peak

Thinner :

RV-372 (Terpineol)

Warranty:

Material guaranteed to meet specifications
for 6 months from date of shipment.

Storage :

Store in a dry location at 5-25°C.

DO NOT REFRIGERATE.

Allow paste to come to room temperature
prior to opening.
Spatulate well before using.

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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application.

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